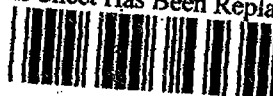


ABSTRACT OF THE DISCLOSURE

Polyimide layers having special properties are formed on the bottom surface of a metallic body for a metal-based semiconductor circuit substrate with a polyimide layer as an insulator. There are four lamination methods: (a) a method in which a layer of thermoplastic polyimide resin (1) and a layer of non-thermoplastic polyimide resin are laminated on the bottom surface of the metallic body one over another in this order, (b) a method in which a layer of thermoplastic polyimide resin (1), a layer of non-thermoplastic polyimide resin and a layer of thermoplastic polyimide resin (2) are laminated on the bottom surface of a metallic body one over another in this order, (c) a method in which a layer of non-thermoplastic polyimide resin is laminated on the bottom surface of a metallic body and (d) a method in which a layer of thermoplastic polyimide resin (2) is laminated on the bottom surface of a metallic body. The resulting semiconductor circuit substrate has improved properties: flat joins to connect external terminals, small variations in shape due to temperature changes, the mounting properties to a mother board, the absorption efficiency of infrared rays during solder reflowing, plating resistance and the bonding reliability to other objects.

This Sheet Has Been Replaced



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REPLACED